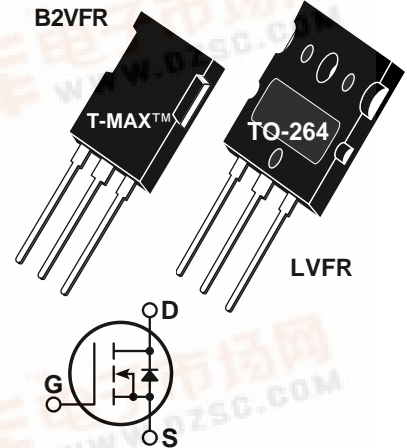




APT10M11B2VFR APT10M11LVFR

100V 100A 0.011Ω

POWER MOS V[®]



Power MOS V[®] is a new generation of high voltage N-Channel enhancement mode power MOSFETs. This new technology minimizes the JFET effect, increases packing density and reduces the on-resistance. Power MOS V[®] also achieves faster switching speeds through optimized gate layout.

- Identical Specifications: T-MAX™ or TO-264 Package
- Lower Leakage
- Fast Recovery Body Diode
- Faster Switching
- 100% Avalanche Tested

MAXIMUM RATINGS

All Ratings: T_C = 25°C unless otherwise specified.

Symbol	Parameter	APT10M11	UNIT
V _{DSS}	Drain-Source Voltage	100	Volts
I _D	Continuous Drain Current @ T _C = 25°C ^⑤	100	Amps
I _{DM}	Pulsed Drain Current ^{① ⑤}	400	
V _{GS}	Gate-Source Voltage Continuous	±30	Volts
V _{GSM}	Gate-Source Voltage Transient	±40	
P _D	Total Power Dissipation @ T _C = 25°C	520	Watts
	Linear Derating Factor	4.16	
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to 150	°C
T _L	Lead Temperature: 0.063" from Case for 10 Sec.	300	
I _{AR}	Avalanche Current ^{① ⑤} (Repetitive and Non-Repetitive)	100	Amps
E _{AR}	Repetitive Avalanche Energy ^①	50	mJ
E _{AS}	Single Pulse Avalanche Energy ^④	2500	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV _{DSS}	Drain-Source Breakdown Voltage (V _{GS} = 0V, I _D = 250μA)	100			Volts
I _{D(on)}	On State Drain Current ^{② ⑤} (V _{DS} > I _{D(on)} × R _{DS(on)} Max, V _{GS} = 10V)	100			Amps
R _{DS(on)}	Drain-Source On-State Resistance ^② (V _{GS} = 10V, 0.5 I _{D[Cont.]})			0.011	Ohms
I _{DSS}	Zero Gate Voltage Drain Current (V _{DS} = V _{DSS} , V _{GS} = 0V)			250	μA
	Zero Gate Voltage Drain Current (V _{DS} = 0.8 V _{DSS} , V _{GS} = 0V, T _C = 125°C)			1000	
I _{GSS}	Gate-Source Leakage Current (V _{GS} = ±30V, V _{DS} = 0V)			±100	nA
V _{GS(th)}	Gate Threshold Voltage (V _{DS} = V _{GS} , I _D = 2.5mA)	2		4	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - <http://www.advancedpower.com>

DYNAMIC CHARACTERISTICS

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Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C _{iss}	Input Capacitance	V _{GS} = 0V V _{DS} = 25V f = 1 MHz		8600	10300	pF
C _{oss}	Output Capacitance			3200	4480	
C _{rss}	Reverse Transfer Capacitance			1180	1770	
Q _g	Total Gate Charge ③	V _{GS} = 10V V _{DD} = 0.5 V _{DSS} I _D = I _D [Cont.] @ 25°C		300	450	nC
Q _{gs}	Gate-Source Charge			95	145	
Q _{gd}	Gate-Drain ("Miller") Charge			110	165	
t _{d(on)}	Turn-on Delay Time	V _{GS} = 15V V _{DD} = 0.5 V _{DSS} I _D = I _D [Cont.] @ 25°C R _G = 0.6Ω		16	32	ns
t _r	Rise Time			33	66	
t _{d(off)}	Turn-off Delay Time			46	70	
t _f	Fall Time			8	16	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
I _S	Continuous Source Current (Body Diode)			100	Amps
I _{SM}	Pulsed Source Current ① (Body Diode)			400	
V _{SD}	Diode Forward Voltage ② (V _{GS} = 0V, I _S = -I _D [Cont.])			1.3	Volts
dv/dt	Peak Diode Recovery dv/dt ⑥			5	V/ns
t _{rr}	Reverse Recovery Time (I _S = -I _D [Cont.], di/dt = 100A/μs)	T _j = 25°C		220	ns
		T _j = 125°C		420	
Q _{rr}	Reverse Recovery Charge (I _S = -I _D [Cont.], di/dt = 100A/μs)	T _j = 25°C		0.8	μC
		T _j = 125°C		3.0	
I _{RRM}	Peak Recovery Current (I _S = -I _D [Cont.], di/dt = 100A/μs)	T _j = 25°C		10	Amps
		T _j = 125°C		18	

THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
R _{θJC}	Junction to Case			0.24	°C/W
R _{θJA}	Junction to Ambient			40	

① Repetitive Rating: Pulse width limited by maximum T_j

② Pulse Test: Pulse width < 380 μs, Duty Cycle < 2%

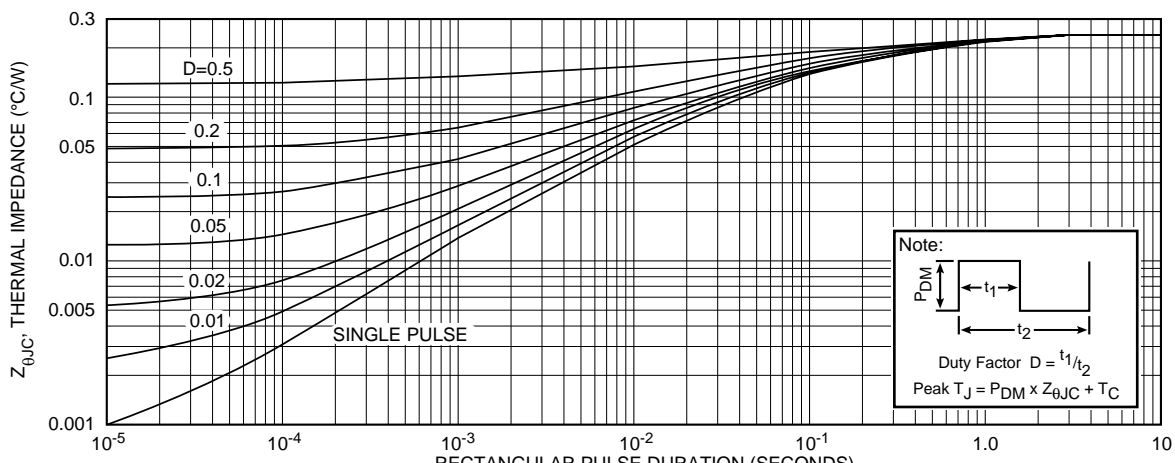
③ See MIL-STD-750 Method 3471

④ Starting T_j = +25°C, L = 500μH, R_G = 25Ω, Peak I_L = 100A

⑤ The maximum current is limited by lead temperature.

⑥ I_S ≤ -I_D [Cont.], di/dt = 100A/μs, V_R = 50V, T_j ≤ 150°C, R_G = 2.0Ω

APT Reserves the right to change, without notice, the specifications and information contained herein.



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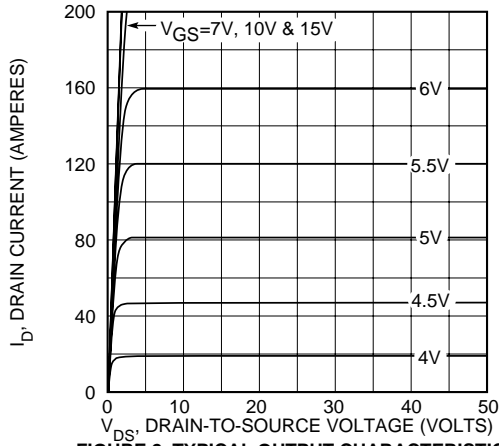


FIGURE 2, TYPICAL OUTPUT CHARACTERISTICS

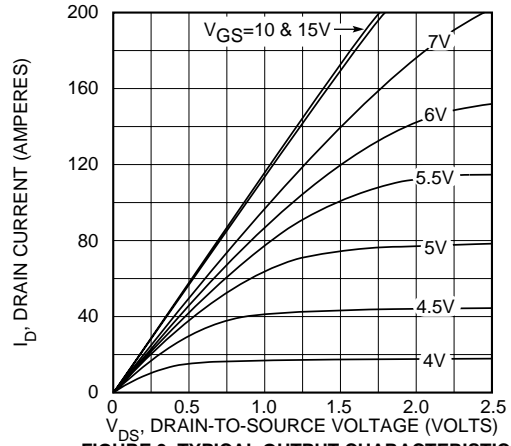


FIGURE 3, TYPICAL OUTPUT CHARACTERISTICS

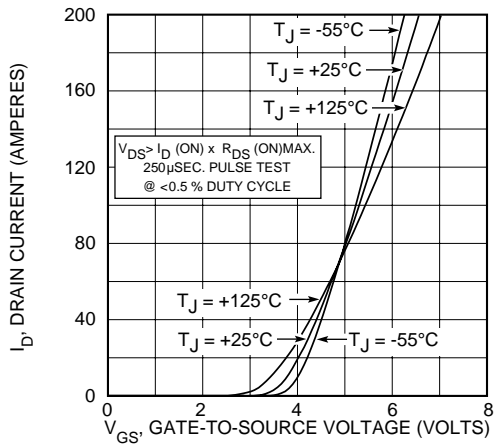


FIGURE 4, TYPICAL TRANSFER CHARACTERISTICS

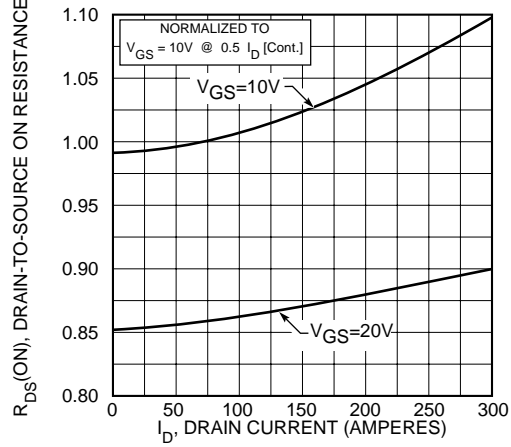


FIGURE 5, $R_{DS(ON)}$ vs DRAIN CURRENT

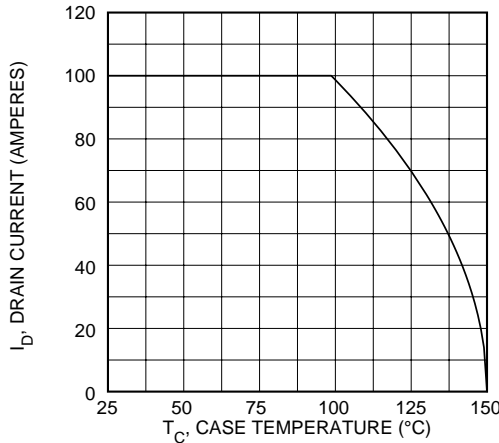


FIGURE 6, MAXIMUM DRAIN CURRENT vs CASE TEMPERATURE

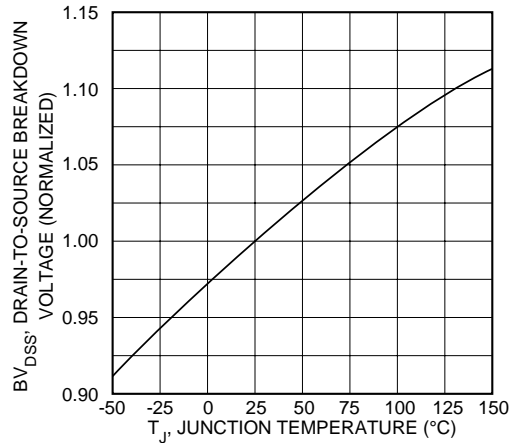


FIGURE 7, BREAKDOWN VOLTAGE vs TEMPERATURE

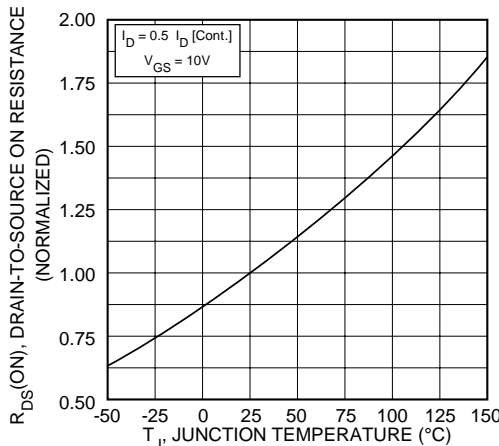


FIGURE 8, ON-RESISTANCE vs. TEMPERATURE

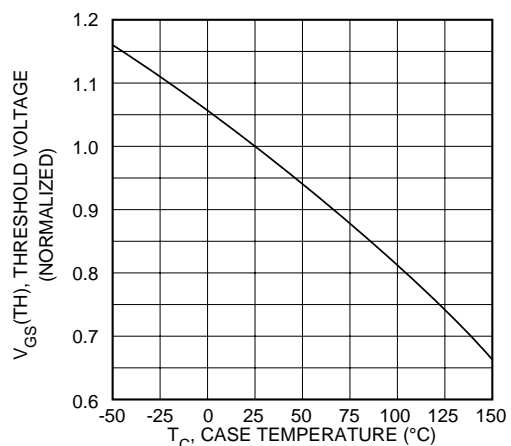


FIGURE 9, THRESHOLD VOLTAGE vs TEMPERATURE

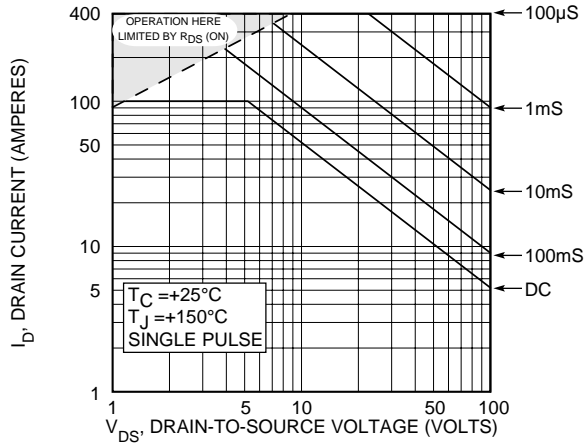


FIGURE 10, MAXIMUM SAFE OPERATING AREA

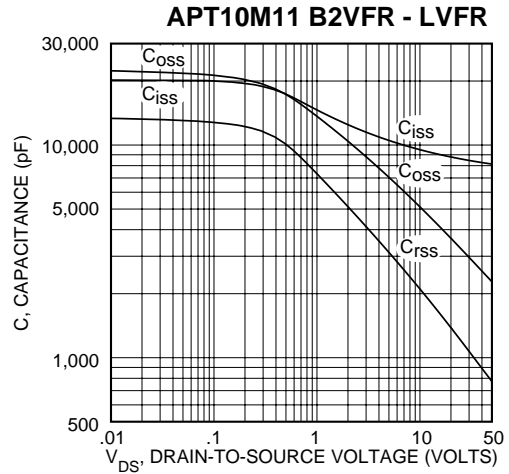


FIGURE 11, TYPICAL CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE

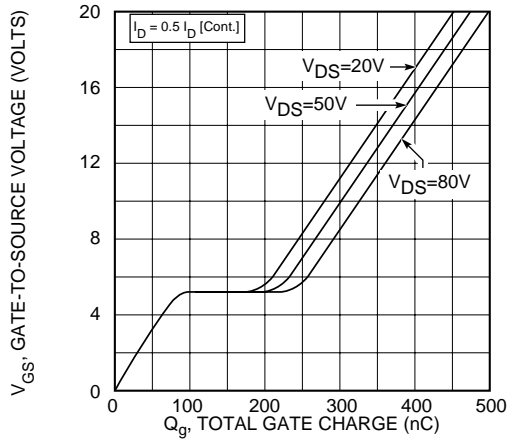


FIGURE 12, GATE CHARGES vs GATE-TO-SOURCE VOLTAGE

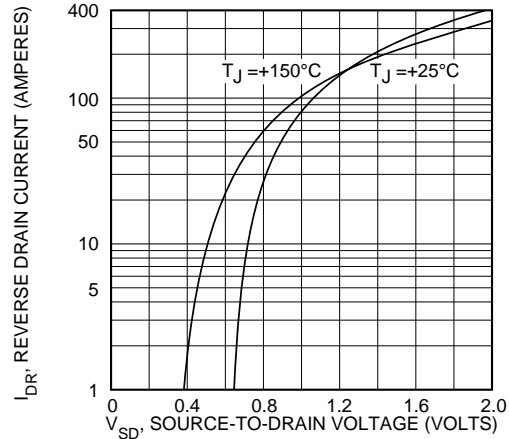


FIGURE 13, TYPICAL SOURCE-DRAIN DIODE FORWARD VOLTAGE

